

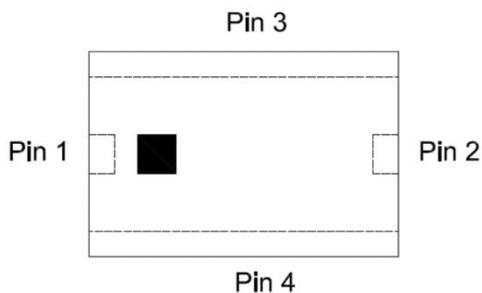
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

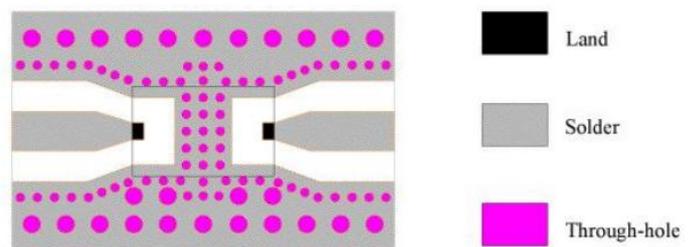
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	1300~2300		1.7
2	Attenuation (dBC)	1100	30	
		1200	8	
3	VSWR	1300~2300		1.6
4	Phase consistency (°)	1300~2300	±5	
5	In/Output Impedance ( $\Omega$ )		50	

### Construction



PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

### Mounting Considerations



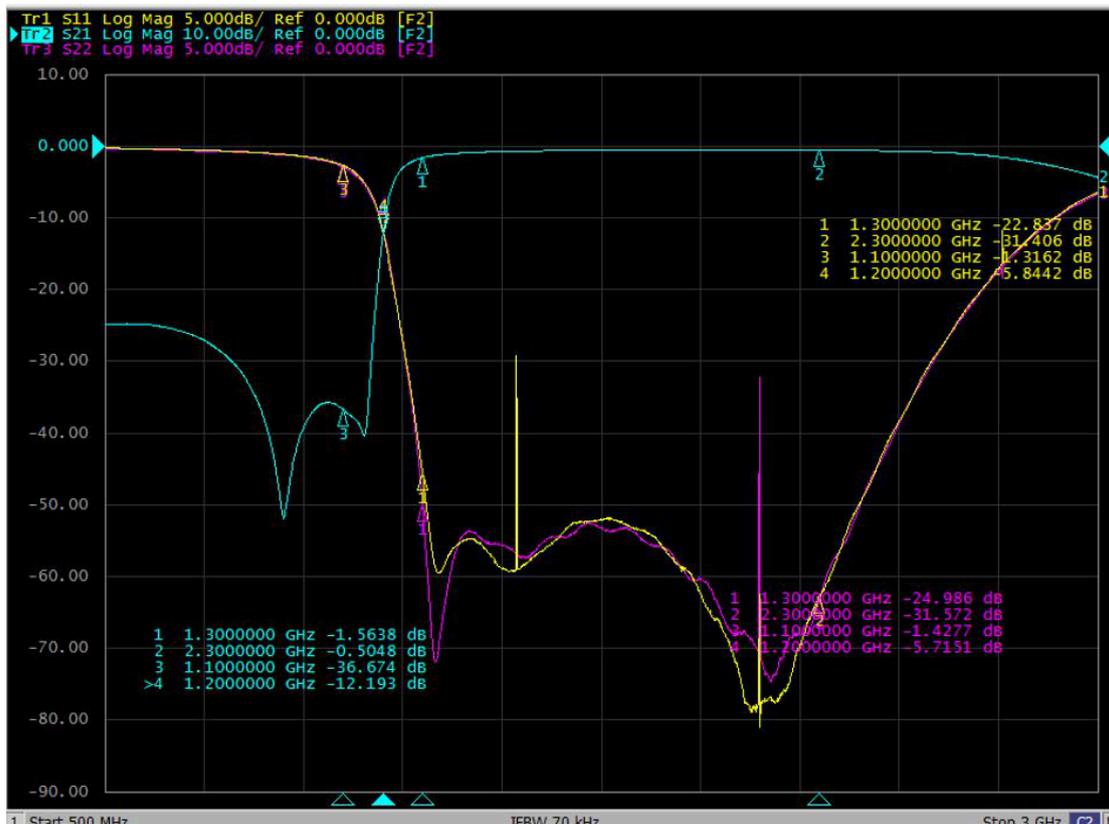
Unit: mm

Line width to be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness

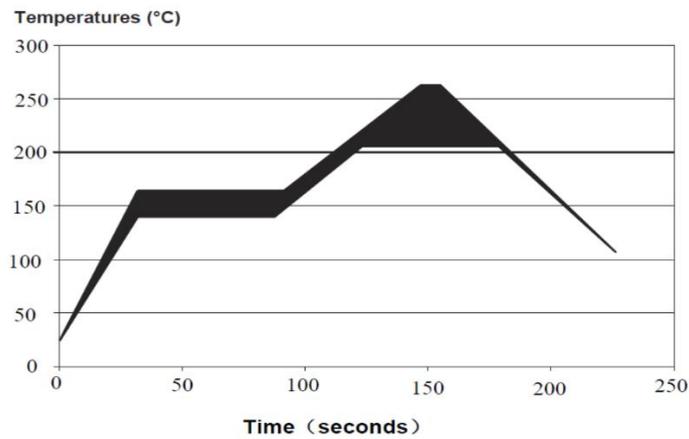
### Dimensions

Figure	Symbol	Dimension (mm)
Top view	L	5.0±0.10
	W	3.2±0.10
Bottom view	T	1.2±0.10
	A	0.60±0.10
	B	0.40±0.10
Side view	C	0.4±0.10

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.